COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP10974</th>
<th>REV: A</th>
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<td>GENERATED : 3/16/2015 10:29:13 AM</td>
<td>TEXAS INSTRUMENTS</td>
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